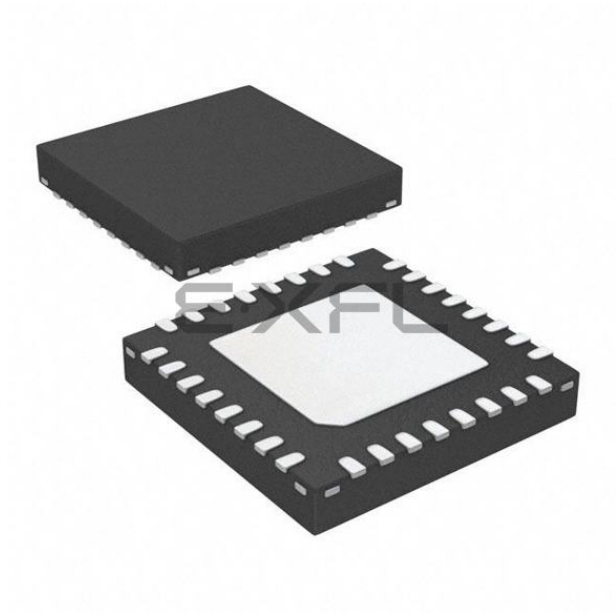

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	28
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VQFN Exposed Pad
Supplier Device Package	32-HVQFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc1114jhn33-203e

- LPC1100L series available as TSSOP28 package, DIP28 package, TSSOP20 package, and SO20 package.
- Extended temperature (−40 °C to +105 °C) for selected parts (see Table 2).

3. Applications

- eMetering
- Alarm systems
- Lighting
- White goods

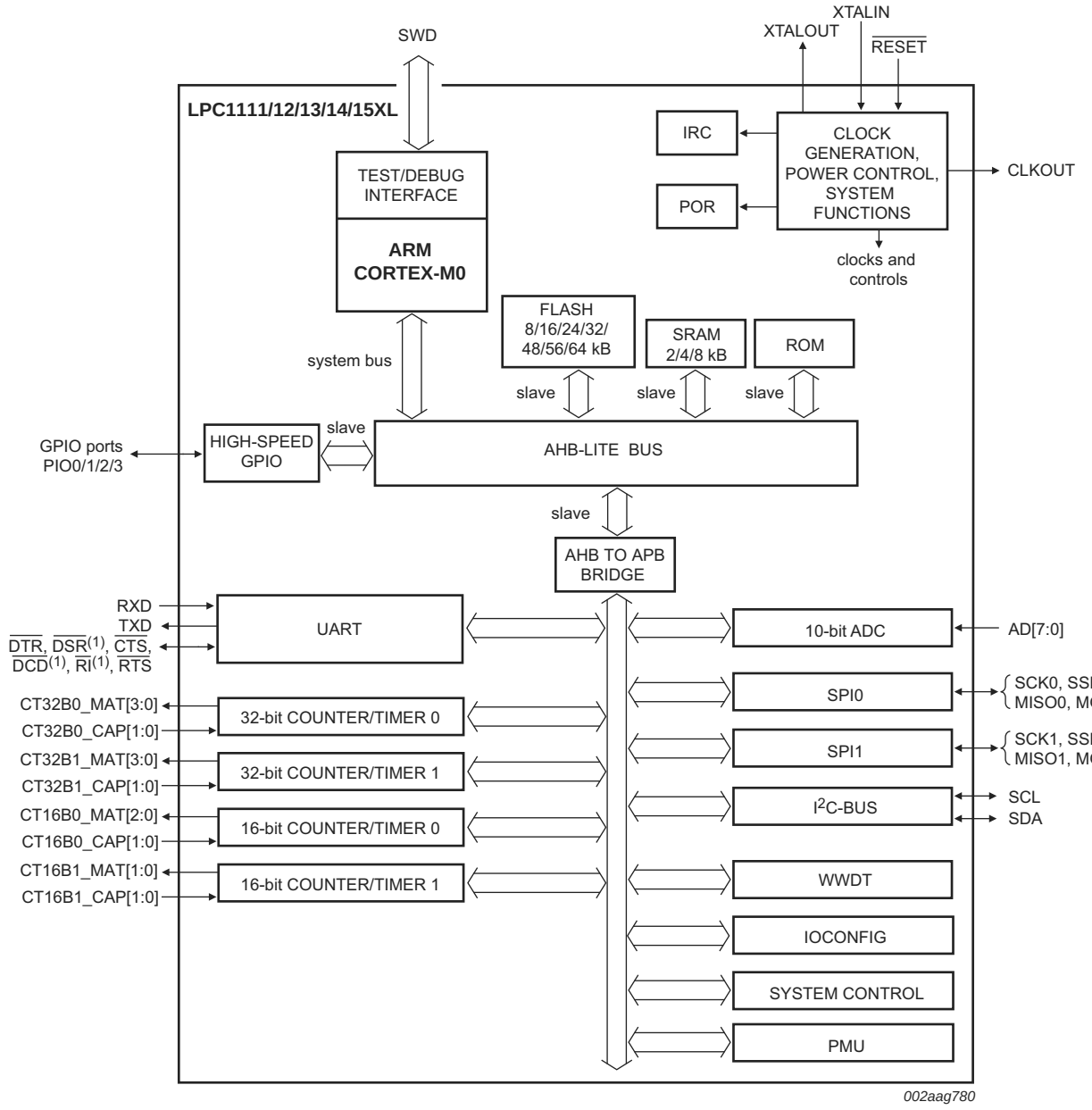
4. Ordering information

Table 1. Ordering information

Type number	Package		
	Name	Description	Version
SO20, TSSOP20, TSSOP28, and DIP28 packages			
LPC1110FD20	SO20	SO20: plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
LPC1111FDH20/002	TSSOP20	TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
LPC1112FD20/102	SO20	SO20: plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
LPC1112FDH20/102	TSSOP20	TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
LPC1112FDH28/102	TSSOP28	TSSOP28: plastic thin shrink small outline package; 28 leads; body width 4.4 mm	SOT361-1
LPC1114FDH28/102	TSSOP28	TSSOP28: plastic thin shrink small outline package; 28 leads; body width 4.4 mm	SOT361-1
LPC1114FN28/102	DIP28	DIP28: plastic dual in-line package; 28 leads (600 mil)	SOT117-1
HVQFN24/33, LQFP48, and TFBGA48 packages			
LPC1111FHN33/101	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1111FHN33/102	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1111FHN33/201	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1111FHN33/202	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1111FHN33/103	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1111JHN33/103	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1111FHN33/203	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1111JHN33/203	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1112FHN33/101	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1112FHN33/102	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a

Table 2. Ordering options *…continued*

Type number	Series	Flash	Total SRAM	Power profiles	UART	I^2C/ Fast+	SPI	ADC channel	GPIO	Package	Temp[1]
LPC1113											
LPC1113FHN33/201	LPC1100	24 kB	4 kB	no	1	1	1	8	28	HVQFN33	F
LPC1113FHN33/202	LPC1100L	24 kB	4 kB	yes	1	1	1	8	28	HVQFN33	F
LPC1113FHN33/203	LPC1100XL	24 kB	4 kB	yes	1	1	2	8	28	HVQFN33	F
LPC1113JHN33/203	LPC1100XL	24 kB	4 kB	yes	1	1	2	8	28	HVQFN33	J
LPC1113FHN33/301	LPC1100	24 kB	8 kB	no	1	1	1	8	28	HVQFN33	F
LPC1113FHN33/302	LPC1100L	24 kB	8 kB	yes	1	1	1	8	28	HVQFN33	F
LPC1113FHN33/303	LPC1100XL	24 kB	8 kB	yes	1	1	2	8	28	HVQFN33	F
LPC1113JHN33/303	LPC1100XL	24 kB	8 kB	yes	1	1	2	8	28	HVQFN33	J
LPC1113FBD48/301	LPC1100	24 kB	8 kB	no	1	1	2	8	42	LQFP48	F
LPC1113FBD48/302	LPC1100L	24 kB	8 kB	yes	1	1	2	8	42	LQFP48	F
LPC1113FBD48/303	LPC1100XL	24 kB	8 kB	yes	1	1	2	8	42	LQFP48	F
LPC1113JBD48/303	LPC1100XL	24 kB	8 kB	yes	1	1	2	8	42	LQFP48	J
LPC1114											
LPC1114FDH28/102	LPC1100L	32 kB	4 kB	yes	1	1	1	6	22	TSSOP28	F
LPC1114FN28/102	LPC1100L	32 kB	4 kB	yes	1	1	1	6	22	DIP28	F
LPC1114FHN33/201	LPC1100	32 kB	4 kB	no	1	1	1	8	28	HVQFN33	F
LPC1114FHN33/202	LPC1100L	32 kB	4 kB	yes	1	1	1	8	28	HVQFN33	F
LPC1114FHN33/203	LPC1100XL	32 kB	4 kB	yes	1	1	2	8	28	HVQFN33	F
LPC1114JHN33/203	LPC1100XL	32 kB	4 kB	yes	1	1	2	8	28	HVQFN33	J
LPC1114FHN33/301	LPC1100	32 kB	8 kB	no	1	1	1	8	28	HVQFN33	F
LPC1114FHN33/302	LPC1100L	32 kB	8 kB	yes	1	1	1	8	28	HVQFN33	F
LPC1114FHN33/303	LPC1100XL	32 kB	8 kB	yes	1	1	2	8	28	HVQFN33	F
LPC1114JHN33/303	LPC1100XL	32 kB	8 kB	yes	1	1	2	8	28	HVQFN33	J
LPC1114FHN33/333	LPC1100XL	56 kB	8 kB	yes	1	1	2	8	28	HVQFN33	F
LPC1114JHN33/333	LPC1100XL	56 kB	8 kB	yes	1	1	2	8	28	HVQFN33	J
LPC1114FHI33/302	LPC1100L	32 kB	8 kB	yes	1	1	1	8	28	HVQFN33	F
LPC1114FHI33/303	LPC1100XL	32 kB	8 kB	yes	1	1	2	8	28	HVQFN33	F
LPC1114JHI33/303	LPC1100XL	32 kB	8 kB	yes	1	1	2	8	28	HVQFN33	J
LPC1114FBD48/301	LPC1100	32 kB	8 kB	no	1	1	2	8	42	LQFP48	F
LPC1114FBD48/302	LPC1100L	32 kB	8 kB	yes	1	1	2	8	42	LQFP48	F
LPC1114FBD48/303	LPC1100XL	32 kB	8 kB	yes	1	1	2	8	42	LQFP48	F
LPC1114JBD48/303	LPC1100XL	32 kB	8 kB	yes	1	1	2	8	42	LQFP48	J
LPC1114FBD48/323	LPC1100XL	48 kB	8 kB	yes	1	1	2	8	42	LQFP48	F
LPC1114JBD48/323	LPC1100XL	48 kB	8 kB	yes	1	1	2	8	42	LQFP48	J
LPC1114FBD48/333	LPC1100XL	56 kB	8 kB	yes	1	1	2	8	42	LQFP48	F
LPC1114JBD48/333	LPC1100XL	56 kB	8 kB	yes	1	1	2	8	42	LQFP48	J
LPC1115											
LPC1115FBD48/303	LPC1100XL	64 kB	8 kB	yes	1	1	2	8	42	LQFP48	F



(1) LQFP48 and TFBGA48 only.

Fig 2. LPC1100XL series block diagram

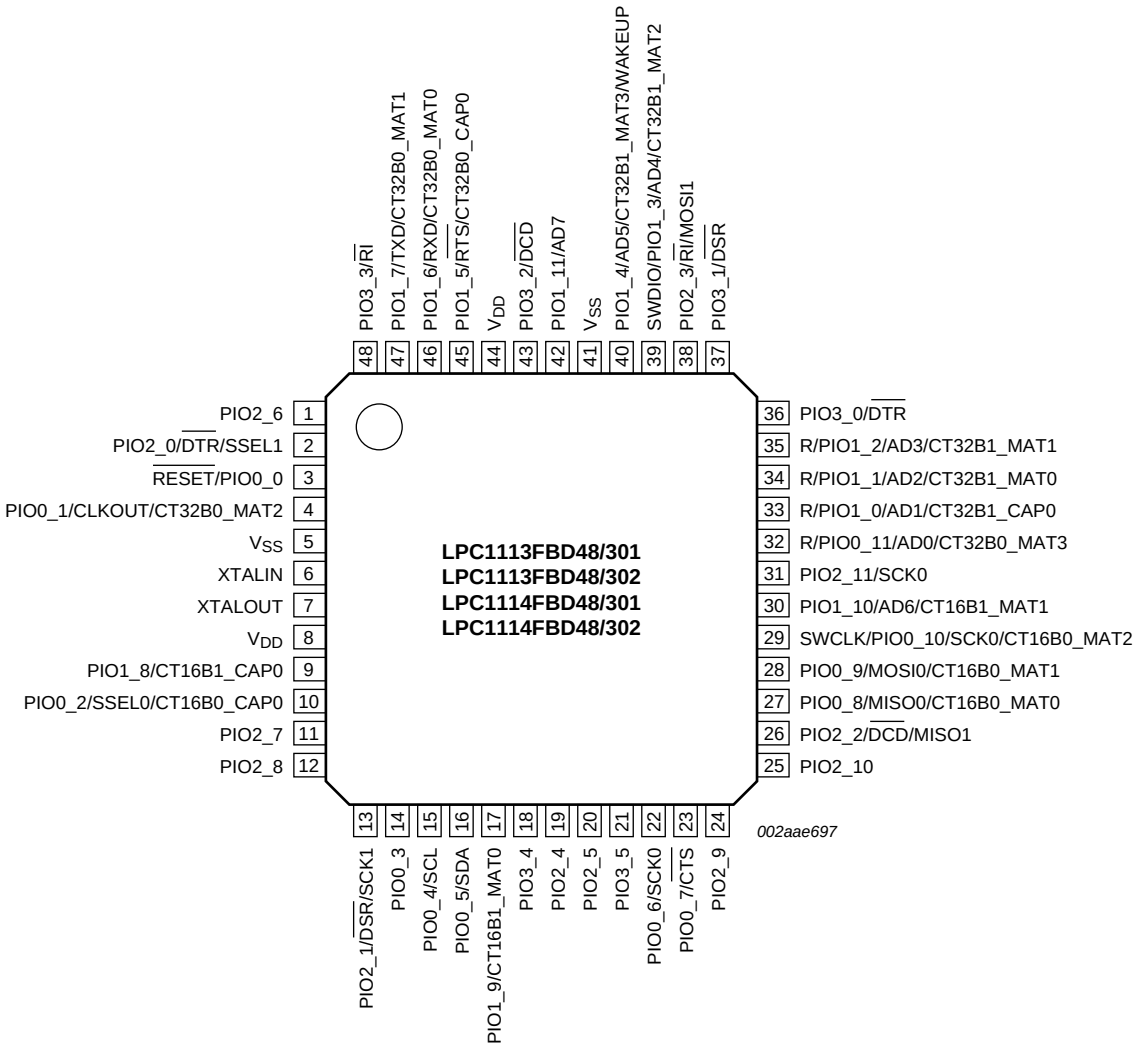


Fig 3. LPC1100 and LPC1100L series pin configuration LQFP48 package

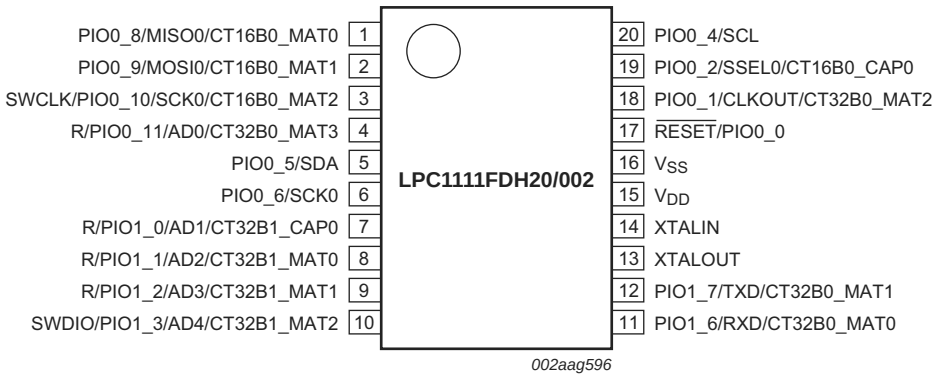


Fig 9. LPC1100L series pin configuration TSSOP20 package with I²C-bus pins

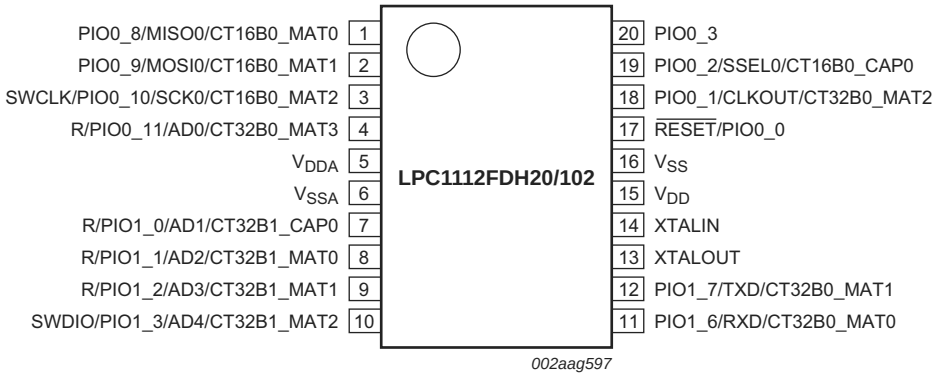


Fig 10. LPC1100L series pin configuration TSSOP20 package with V_{DDA} and V_{SSA} pins

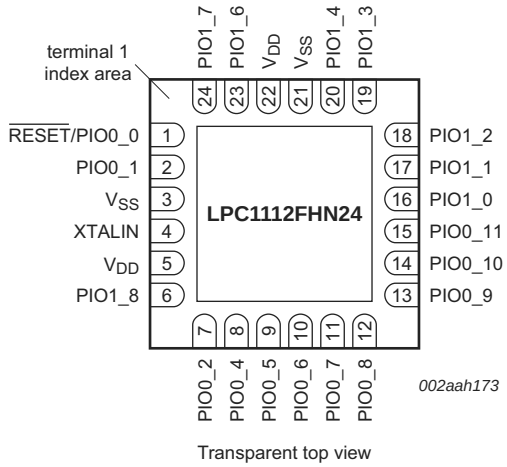


Fig 11. LPC1100L series pin configuration HVQFN24 package

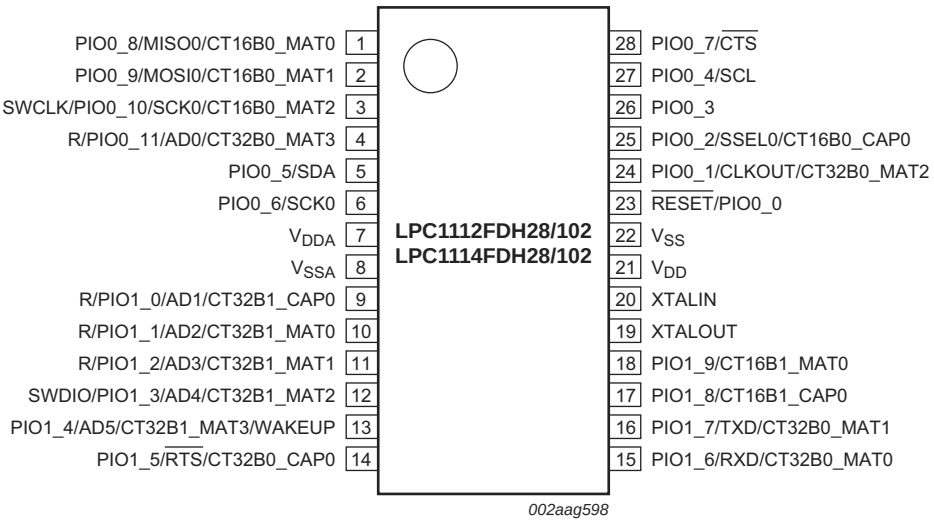


Fig 12. LPC1100L pin configuration TSSOP28 package

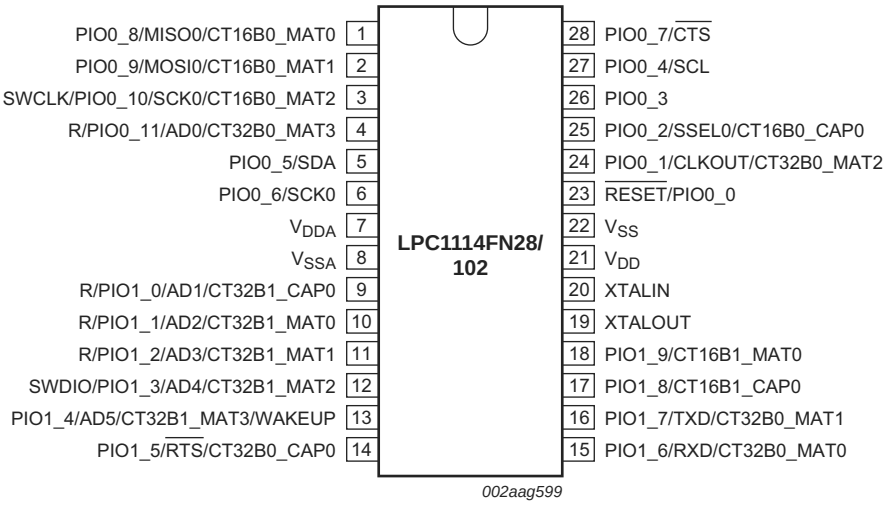


Fig 13. LPC1100L series pin configuration DIP28 package

Table 4. LPC1100L series: LPC1110/11/12 pin description table (SO20 and TSSOP20 package with I²C-bus pins) *…continued*

Symbol	Pin SO20/ TSSOP20	Start logic input	Type	Reset state [1]	Description
R/PIO0_11/ AD0/CT32B0_MAT3	4 [5]	yes	I	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	**PIO0_11 —** General purpose digital input/output pin.
			I	-	**AD0 —** A/D converter, input 0.
			O	-	**CT32B0_MAT3 —** Match output 3 for 32-bit timer 0.
PIO1_0 to PIO1_7			I/O		**Port 1 —** Port 1 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 1 pins depends on the function selected through the IOCONFIG register block.
R/PIO1_0/ AD1/CT32B1_CAP0	7 [5]	yes	I	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	**PIO1_0 —** General purpose digital input/output pin.
			I	-	**AD1 —** A/D converter, input 1.
			I	-	**CT32B1_CAP0 —** Capture input 0 for 32-bit timer 1.
R/PIO1_1/ AD2/CT32B1_MAT0	8 [5]	no	O	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	**PIO1_1 —** General purpose digital input/output pin.
			I	-	**AD2 —** A/D converter, input 2.
			O	-	**CT32B1_MAT0 —** Match output 0 for 32-bit timer 1.
R/PIO1_2/ AD3/CT32B1_MAT1	9 [5]	no	I	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	**PIO1_2 —** General purpose digital input/output pin.
			I	-	**AD3 —** A/D converter, input 3.
			O	-	**CT32B1_MAT1 —** Match output 1 for 32-bit timer 1.
SWDIO/PIO1_3/ AD4/CT32B1_MAT2	10 [5]	no	I/O	I; PU	**SWDIO —** Serial wire debug input/output.
			I/O	-	**PIO1_3 —** General purpose digital input/output pin.
			I	-	**AD4 —** A/D converter, input 4.
			O	-	**CT32B1_MAT2 —** Match output 2 for 32-bit timer 1.
PIO1_6/RXD/ CT32B0_MAT0	11 [3]	no	I/O	I; PU	**PIO1_6 —** General purpose digital input/output pin.
			I	-	**RXD —** Receiver input for UART.
			O	-	**CT32B0_MAT0 —** Match output 0 for 32-bit timer 0.
PIO1_7/TXD/ CT32B0_MAT1	12 [3]	no	I/O	I; PU	**PIO1_7 —** General purpose digital input/output pin.
			O	-	**TXD —** Transmitter output for UART.
			O	-	**CT32B0_MAT1 —** Match output 1 for 32-bit timer 0.
V_{DD}	15	-		-	3.3 V supply voltage to the internal regulator, the external rail, and the ADC. Also used as the ADC reference voltage.
XTALIN	14 [6]	-	I	-	Input to the oscillator circuit and internal clock generator circuits. Input voltage must not exceed 1.8 V.
XTALOUT	13 [6]	-	O	-	Output from the oscillator amplifier.
V_{SS}	16	-		-	Ground.

Table 7. LPC1100L series: LPC1112/14 pin description table (TSSOP28 and DIP28 packages) *…continued*

Symbol	Pin TSSOP28/ DIP28	Start logic input	Type	Reset state [1]	Description
PIO1_5/$\overline{\text{RTS}}$/ CT32B0_CAP0	14 [3]	no	I/O	I; PU	**PIO1_5 —** General purpose digital input/output pin.
			O	-	**$\overline{\text{RTS}}$ —** Request To Send output for UART.
			I	-	**CT32B0_CAP0 —** Capture input 0 for 32-bit timer 0.
PIO1_6/RXD/ CT32B0_MAT0	15 [3]	no	I/O	I; PU	**PIO1_6 —** General purpose digital input/output pin.
			I	-	**RXD —** Receiver input for UART.
			O	-	**CT32B0_MAT0 —** Match output 0 for 32-bit timer 0.
PIO1_7/TXD/ CT32B0_MAT1	16 [3]	no	I/O	I; PU	**PIO1_7 —** General purpose digital input/output pin.
			O	-	**TXD —** Transmitter output for UART.
			O	-	**CT32B0_MAT1 —** Match output 1 for 32-bit timer 0.
PIO1_8/ CT16B1_CAP0	17 [3]	no	I/O	I; PU	**PIO1_8 —** General purpose digital input/output pin.
			I	-	**CT16B1_CAP0 —** Capture input 0 for 16-bit timer 1.
PIO1_9/ CT16B1_MAT0	18 [3]	no	I/O	I; PU	**PIO1_9 —** General purpose digital input/output pin.
			O	-	**CT16B1_MAT0 —** Match output 0 for 16-bit timer 1.
V_{DD}	21	-		-	3.3 V supply voltage to the internal regulator and the external rail.
V_{DDA}	7	-	-	-	3.3 V supply voltage to the ADC. Also used as the ADC reference voltage.
XTALIN	20 [6]	-	I	-	Input to the oscillator circuit and internal clock generator circuits. Input voltage must not exceed 1.8 V.
XTALOUT	19 [6]	-	O	-	Output from the oscillator amplifier.
V_{SS}	22	-		-	Ground.
V_{SSA}	8	-	-	-	Analog ground.

[1] Pin state at reset for default function: I = Input; O = Output; PU = internal pull-up enabled (pins pulled up to full V_{DD} level); IA = inactive, no pull-up/down enabled.

[2] 5 V tolerant pad. $\overline{\text{RESET}}$ functionality is not available in Deep power-down mode. Use the WAKEUP pin to reset the chip and wake up from Deep power-down mode. An external pull-up resistor is required on this pin for the Deep power-down mode. See Figure 52 for the reset pad configuration.

[3] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors and configurable hysteresis (see Figure 51).

[4] I^2C-bus pads compliant with the I^2C-bus specification for I^2C standard mode and I^2C Fast-mode Plus. The pin requires an external pull-up to provide output functionality. When power is switched off, this pin is floating and does not disturb the I2C lines. Open-drain configuration applies to all functions on this pin.

[5] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors, configurable hysteresis, and analog input. When configured as a ADC input, digital section of the pad is disabled and the pin is not 5 V tolerant (see Figure 51).

[6] When the system oscillator is not used, connect XTALIN and XTALOUT as follows: XTALIN can be left floating or can be grounded (grounding is preferred to reduce susceptibility to noise). XTALOUT should be left floating.

Table 8. LPC1100 and LPC1100L series: LPC1113/14 pin description table (LQFP48 package)

Symbol	Pin	Start logic input	Type	Reset state [1]	Description
PIO0_0 to PIO0_11			I/O		**Port 0 —** Port 0 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 0 pins depends on the function selected through the IOCONFIG register block.
$\overline{\text{RESET}}$/PIO0_0	3[2]	yes	I	I; PU	**$\overline{\text{RESET}}$ —** External reset input with 20 ns glitch filter. A LOW-going pulse as short as 50 ns on this pin resets the device, causing I/O ports and peripherals to take on their default states, and processor execution to begin at address 0. In deep power-down mode, this pin must be pulled HIGH externally. The $\overline{\text{RESET}}$ pin can be left unconnected or be used as a GPIO pin if an external $\overline{\text{RESET}}$ function is not needed and Deep power-down mode is not used.
			I/O	-	**PIO0_0 —** General purpose digital input/output pin with 10 ns glitch filter.
PIO0_1/CLKOUT/ CT32B0_MAT2	4[3]	yes	I/O	I; PU	**PIO0_1 —** General purpose digital input/output pin. A LOW level on this pin during reset starts the ISP command handler.
			O	-	**CLKOUT —** Clockout pin.
			O	-	**CT32B0_MAT2 —** Match output 2 for 32-bit timer 0.
PIO0_2/SSEL0/ CT16B0_CAP0	10[3]	yes	I/O	I; PU	**PIO0_2 —** General purpose digital input/output pin.
			I/O	-	**SSEL0 —** Slave Select for SPI0.
			I	-	**CT16B0_CAP0 —** Capture input 0 for 16-bit timer 0.
PIO0_3	14[3]	yes	I/O	I; PU	**PIO0_3 —** General purpose digital input/output pin.
PIO0_4/SCL	15[4]	yes	I/O	I; IA	**PIO0_4 —** General purpose digital input/output pin (open-drain).
			I/O	-	**SCL —** I^2C-bus, open-drain clock input/output. High-current sink only if I^2C Fast-mode Plus is selected in the I/O configuration register.
PIO0_5/SDA	16[4]	yes	I/O	I; IA	**PIO0_5 —** General purpose digital input/output pin (open-drain).
			I/O	-	**SDA —** I^2C-bus, open-drain data input/output. High-current sink only if I^2C Fast-mode Plus is selected in the I/O configuration register.
PIO0_6/SCK0	22[3]	yes	I/O	I; PU	**PIO0_6 —** General purpose digital input/output pin.
			I/O	-	**SCK0 —** Serial clock for SPI0.
PIO0_7/$\overline{\text{CTS}}$	23[3]	yes	I/O	I; PU	**PIO0_7 —** General purpose digital input/output pin (high-current output driver).
			I	-	**$\overline{\text{CTS}}$ —** Clear To Send input for UART.
PIO0_8/MISO0/ CT16B0_MAT0	27[3]	yes	I/O	I; PU	**PIO0_8 —** General purpose digital input/output pin.
			I/O	-	**MISO0 —** Master In Slave Out for SPI0.
			O	-	**CT16B0_MAT0 —** Match output 0 for 16-bit timer 0.
PIO0_9/MOSI0/ CT16B0_MAT1	28[3]	yes	I/O	I; PU	**PIO0_9 —** General purpose digital input/output pin.
			I/O	-	**MOSI0 —** Master Out Slave In for SPI0.
			O	-	**CT16B0_MAT1 —** Match output 1 for 16-bit timer 0.

Table 9. LPC1100 and LPC1100L series: LPC1111/12/13/14 pin description table (HVQFN33 package)

Symbol	Pin	Start logic input	Type	Reset state [1]	Description
PIO0_0 to PIO0_11					**Port 0 —** Port 0 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 0 pins depends on the function selected through the IOCONFIG register block.
$\overline{\text{RESET}}$/PIO0_0	2[2]	yes	I	I;PU	**$\overline{\text{RESET}}$ —** External reset input with 20 ns glitch filter. A LOW-going pulse as short as 50 ns on this pin resets the device, causing I/O ports and peripherals to take on their default states and processor execution to begin at address 0. In deep power-down mode, this pin must be pulled HIGH externally. The $\overline{\text{RESET}}$ pin can be left unconnected or be used as a GPIO pin if an external $\overline{\text{RESET}}$ function is not needed and Deep power-down mode is not used.
			I/O	-	**PIO0_0 —** General purpose digital input/output pin with 10 ns glitch filter.
PIO0_1/CLKOUT/ CT32B0_MAT2	3[3]	yes	I/O	I;PU	**PIO0_1 —** General purpose digital input/output pin. A LOW level on this pin during reset starts the ISP command handler.
			O	-	**CLKOUT —** Clock out pin.
			O	-	**CT32B0_MAT2 —** Match output 2 for 32-bit timer 0.
PIO0_2/SSEL0/ CT16B0_CAP0	8[3]	yes	I/O	I;PU	**PIO0_2 —** General purpose digital input/output pin.
			I/O	-	**SSEL0 —** Slave select for SPI0.
			I	-	**CT16B0_CAP0 —** Capture input 0 for 16-bit timer 0.
PIO0_3	9[3]	yes	I/O	I;PU	**PIO0_3 —** General purpose digital input/output pin.
PIO0_4/SCL	10[4]	yes	I/O	I;IA	**PIO0_4 —** General purpose digital input/output pin (open-drain).
			I/O	-	**SCL —** I^2C-bus, open-drain clock input/output. High-current sink only if I^2C Fast-mode Plus is selected in the I/O configuration register.
PIO0_5/SDA	11[4]	yes	I/O	I;IA	**PIO0_5 —** General purpose digital input/output pin (open-drain).
			I/O	-	**SDA —** I^2C-bus, open-drain data input/output. High-current sink only if I^2C Fast-mode Plus is selected in the I/O configuration register.
PIO0_6/SCK0	15[3]	yes	I/O	I;PU	**PIO0_6 —** General purpose digital input/output pin.
			I/O	-	**SCK0 —** Serial clock for SPI0.
PIO0_7/$\overline{\text{CTS}}$	16[3]	yes	I/O	I;PU	**PIO0_7 —** General purpose digital input/output pin (high-current output driver).
			I	-	**$\overline{\text{CTS}}$ —** Clear To Send input for UART.
PIO0_8/MISO0/ CT16B0_MAT0	17[3]	yes	I/O	I;PU	**PIO0_8 —** General purpose digital input/output pin.
			I/O	-	**MISO0 —** Master In Slave Out for SPI0.
			O	-	**CT16B0_MAT0 —** Match output 0 for 16-bit timer 0.
PIO0_9/MOSI0/ CT16B0_MAT1	18[3]	yes	I/O	I;PU	**PIO0_9 —** General purpose digital input/output pin.
			I/O	-	**MOSI0 —** Master Out Slave In for SPI0.
			O	-	**CT16B0_MAT1 —** Match output 1 for 16-bit timer 0.
SWCLK/PIO0_10/ SCK0/ CT16B0_MAT2	19[3]	yes	I	I;PU	**SWCLK —** Serial wire clock.
			I/O	-	**PIO0_10 —** General purpose digital input/output pin.
			I/O	-	**SCK0 —** Serial clock for SPI0.
			O	-	**CT16B0_MAT2 —** Match output 2 for 16-bit timer 0.

Table 10. LPC1100XL series: LPC1113/14/15 pin description table (LQFP48 and TFBGA48 package) *…continued*

Symbol	LQFP48	TFBGA48	Start logic input	Type	Reset state [1]	Description
PIO0_8/MISO0/ CT16B0_MAT0	27[3]	F8[3]	yes	I/O	I; PU	**PIO0_8 —** General purpose digital input/output pin.
				I/O	-	**MISO0 —** Master In Slave Out for SPI0.
				O	-	**CT16B0_MAT0 —** Match output 0 for 16-bit timer 0.
PIO0_9/MOSI0/ CT16B0_MAT1	28[3]	F7[3]	yes	I/O	I; PU	**PIO0_9 —** General purpose digital input/output pin.
				I/O	-	**MOSI0 —** Master Out Slave In for SPI0.
				O	-	**CT16B0_MAT1 —** Match output 1 for 16-bit timer 0.
SWCLK/PIO0_10/ SCK0/ CT16B0_MAT2	29[3]	E7[3]	yes	I	I; PU	**SWCLK —** Serial wire clock.
				I/O	-	**PIO0_10 —** General purpose digital input/output pin.
				I/O	-	**SCK0 —** Serial clock for SPI0.
				O	-	**CT16B0_MAT2 —** Match output 2 for 16-bit timer 0.
R/PIO0_11/ AD0/CT32B0_MAT3	32[5]	D8[5]	yes	I	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
				I/O	-	**PIO0_11 —** General purpose digital input/output pin.
				I	-	**AD0 —** A/D converter, input 0.
				O	-	**CT32B0_MAT3 —** Match output 3 for 32-bit timer 0.
PIO1_0 to PIO1_11				I/O		**Port 1 —** Port 1 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 1 pins depends on the function selected through the IOCONFIG register block.
R/PIO1_0/ AD1/CT32B1_CAP0	33[5]	C7[5]	yes	I	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
				I/O	-	**PIO1_0 —** General purpose digital input/output pin.
				I	-	**AD1 —** A/D converter, input 1.
				I	-	**CT32B1_CAP0 —** Capture input 0 for 32-bit timer 1.
R/PIO1_1/ AD2/CT32B1_MAT0	34[5]	C8[5]	no	O	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
				I/O	-	**PIO1_1 —** General purpose digital input/output pin.
				I	-	**AD2 —** A/D converter, input 2.
				O	-	**CT32B1_MAT0 —** Match output 0 for 32-bit timer 1.
R/PIO1_2/ AD3/CT32B1_MAT1	35[5]	B7[5]	no	I	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
				I/O	-	**PIO1_2 —** General purpose digital input/output pin.
				I	-	**AD3 —** A/D converter, input 3.
				O	-	**CT32B1_MAT1 —** Match output 1 for 32-bit timer 1.
SWDIO/PIO1_3/ AD4/CT32B1_MAT2	39[5]	B6[5]	no	I/O	I; PU	**SWDIO —** Serial wire debug input/output.
				I/O	-	**PIO1_3 —** General purpose digital input/output pin.
				I	-	**AD4 —** A/D converter, input 4.
				O	-	**CT32B1_MAT2 —** Match output 2 for 32-bit timer 1.

Table 10. LPC1100XL series: LPC1113/14/15 pin description table (LQFP48 and TFBGA48 package) *…continued*

Symbol	LQFP48	TFBGA48	Start logic input	Type	Reset state [1]	Description
PIO1_4/AD5/ CT32B1_MAT3/ WAKEUP	40[5]	A6[5]	no	I/O	I; PU	**PIO1_4 —** General purpose digital input/output pin with 10 ns glitch filter. In Deep power-down mode, this pin serves as the Deep power-down mode wake-up pin with 20 ns glitch filter. Pull this pin HIGH externally before entering Deep power-down mode. Pull this pin LOW to exit Deep power-down mode. A LOW-going pulse as short as 50 ns wakes up the part.
				I	-	**AD5 —** A/D converter, input 5.
				O	-	**CT32B1_MAT3 —** Match output 3 for 32-bit timer 1.
PIO1_5/$\overline{\text{RTS}}$/ CT32B0_CAP0	45[3]	A3[3]	no	I/O	I; PU	**PIO1_5 —** General purpose digital input/output pin.
				O	-	**$\overline{\text{RTS}}$ —** Request To Send output for UART.
				I	-	**CT32B0_CAP0 —** Capture input 0 for 32-bit timer 0.
PIO1_6/RXD/ CT32B0_MAT0	46[3]	B3[3]	no	I/O	I; PU	**PIO1_6 —** General purpose digital input/output pin.
				I	-	**RXD —** Receiver input for UART.
				O	-	**CT32B0_MAT0 —** Match output 0 for 32-bit timer 0.
PIO1_7/TXD/ CT32B0_MAT1	47[3]	B2[3]	no	I/O	I; PU	**PIO1_7 —** General purpose digital input/output pin.
				O	-	**TXD —** Transmitter output for UART.
				O	-	**CT32B0_MAT1 —** Match output 1 for 32-bit timer 0.
PIO1_8/ CT16B1_CAP0	9[3]	F2[3]	no	I/O	I; PU	**PIO1_8 —** General purpose digital input/output pin.
				I	-	**CT16B1_CAP0 —** Capture input 0 for 16-bit timer 1.
PIO1_9/ CT16B1_MAT0/ MOSI1	17[3]	G4[3]	no	I/O	I; PU	**PIO1_9 —** General purpose digital input/output pin.
				O	-	**CT16B1_MAT0 —** Match output 0 for 16-bit timer 1.
				I/O	-	**MOSI1 —** Master Out Slave In for SPI1.
PIO1_10/AD6/ CT16B1_MAT1/ MISO1	30[5]	E8[5]	no	I/O	I; PU	**PIO1_10 —** General purpose digital input/output pin.
				I	-	**AD6 —** A/D converter, input 6.
				O	-	**CT16B1_MAT1 —** Match output 1 for 16-bit timer 1.
				I/O	-	**MISO1 —** Master In Slave Out for SPI1.
PIO1_11/AD7/ CT32B1_CAP1	42[5]	A5[5]	no	I/O	I; PU	**PIO1_11 —** General purpose digital input/output pin.
				I	-	**AD7 —** A/D converter, input 7.
				I	-	**CT32B1_CAP1 —** Capture input 1 for 32-bit timer 1.
PIO2_0 to PIO2_11				I/O		**Port 2 —** Port 2 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 2 pins depends on the function selected through the IOCONFIG register block.
PIO2_0/$\overline{\text{DTR}}$/SSEL1	2[3]	B1[3]	no	I/O	I; PU	**PIO2_0 —** General purpose digital input/output pin.
				O	-	**$\overline{\text{DTR}}$ —** Data Terminal Ready output for UART.
				I/O	-	**SSEL1 —** Slave Select for SPI1.
PIO2_1/$\overline{\text{DSR}}$/SCK1	13[3]	H1[3]	no	I/O	I; PU	**PIO2_1 —** General purpose digital input/output pin.
				I	-	**$\overline{\text{DSR}}$ —** Data Set Ready input for UART.
				I/O	-	**SCK1 —** Serial clock for SPI1.

The start logic must be configured in the system configuration block and in the NVIC before being used.

7.17.2 Reset

Reset has four sources on the LPC1110/11/12/13/14/15: the $\overline{\text{RESET}}$ pin, the Watchdog reset, Power-On Reset (POR), and the BrownOut Detection (BOD) circuit. The $\overline{\text{RESET}}$ pin is a Schmitt trigger input pin. Assertion of chip reset by any source, once the operating voltage attains a usable level, starts the IRC and initializes the flash controller.

A LOW-going pulse as short as 50 ns resets the part.

When the internal Reset is removed, the processor begins executing at address 0, which is initially the Reset vector mapped from the boot block. At that point, all of the processor and peripheral registers have been initialized to predetermined values.

An external pull-up resistor is required on the $\overline{\text{RESET}}$ pin if Deep power-down mode is used.

7.17.3 Brownout detection

The LPC1110/11/12/13/14/15 includes up to four levels for monitoring the voltage on the V_{DD} pin. If this voltage falls below one of the selected levels, the BOD asserts an interrupt signal to the NVIC. This signal can be enabled for interrupt in the Interrupt Enable Register in the NVIC in order to cause a CPU interrupt; if not, software can monitor the signal by reading a dedicated status register. Four threshold levels can be selected to cause a forced reset of the chip.

7.17.4 Code security (Code Read Protection - CRP)

This feature of the LPC1110/11/12/13/14/15 allows user to enable different levels of security in the system so that access to the on-chip flash and use of the Serial Wire Debugger (SWD) and In-System Programming (ISP) can be restricted. When needed, CRP is invoked by programming a specific pattern into a dedicated flash location. IAP commands are not affected by the CRP.

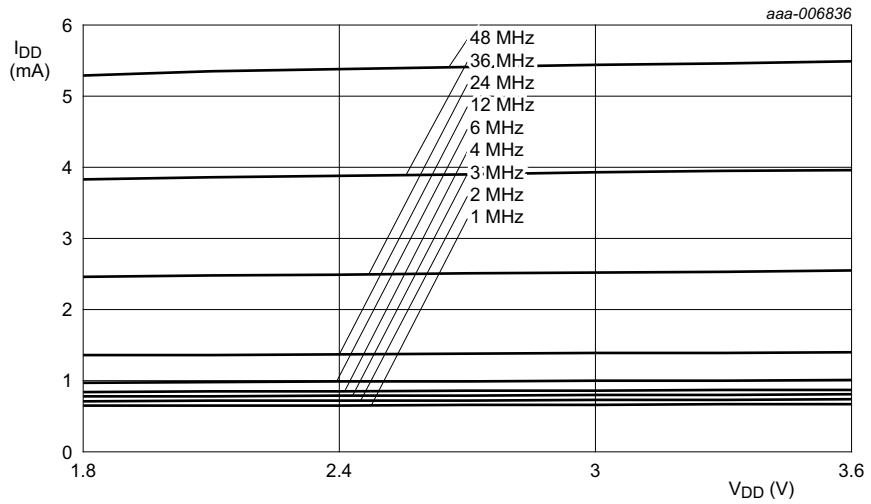
In addition, ISP entry via the PIO0_1 pin can be disabled without enabling CRP. For details see the *LPC111x user manual*.

There are three levels of Code Read Protection:

1. CRP1 disables access to the chip via the SWD and allows partial flash update (excluding flash sector 0) using a limited set of the ISP commands. This mode is useful when CRP is required and flash field updates are needed but all sectors can not be erased.
2. CRP2 disables access to the chip via the SWD and only allows full flash erase and update using a reduced set of the ISP commands.
3. Running an application with level CRP3 selected fully disables any access to the chip via the SWD pins and the ISP. This mode effectively disables ISP override using PIO0_1 pin, too. It is up to the user's application to provide (if needed) flash update mechanism using IAP calls or call reinvoke ISP command to enable flash update via the UART.

Power measurements in Active, Sleep, and Deep-sleep modes were performed under the following conditions (see *LPC111x user manual*):

- Configure all pins as GPIO with pull-up resistor disabled in the IOCONFIG block.
- Configure GPIO pins as outputs using the GPIOnDIR registers.
- Write 0 to all GPIOnDATA registers to drive the outputs LOW.



Conditions: T_{amb} = 25 °C; active mode entered executing code `while(1){}` from flash; all peripherals disabled in the SYSAHBCLKCTRL register (SYSAHBCLKCTRL = 0x1F); all peripheral clocks disabled; internal pull-up resistors disabled; BOD disabled; low-current mode.

1 MHz to 6 MHz: system oscillator enabled; PLL, IRC disabled.

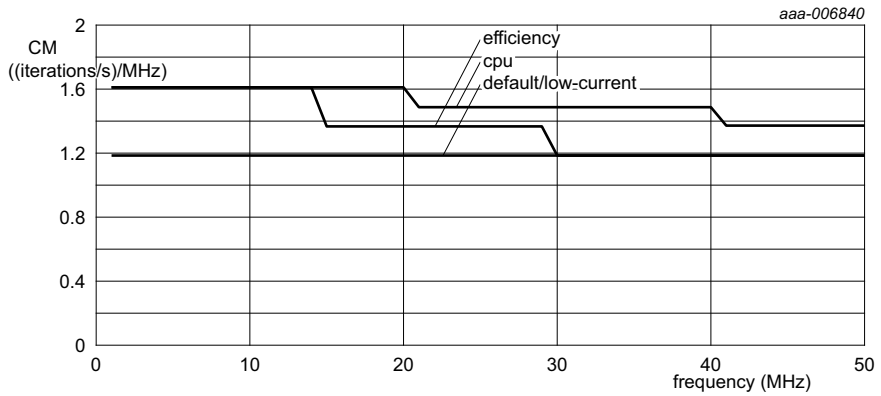
12 MHz: IRC enabled; system oscillator, PLL disabled.

24 MHz to 48 MHz: IRC disabled; system oscillator, PLL enabled.

Fig 28. Active mode: Typical supply current I_{DD} versus supply voltage V_{DD} for different system clock frequencies (for LPC111xXL)

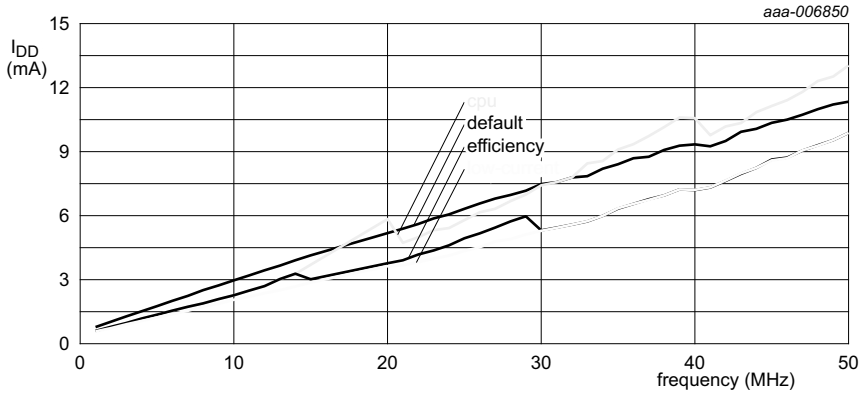
10.8 CoreMark data

Remark: All CoreMark data were taken with the Keil uVision v. 4.6 tool.



V_{DD} = 3.3 V; T = 25 °C; active mode; typical samples.

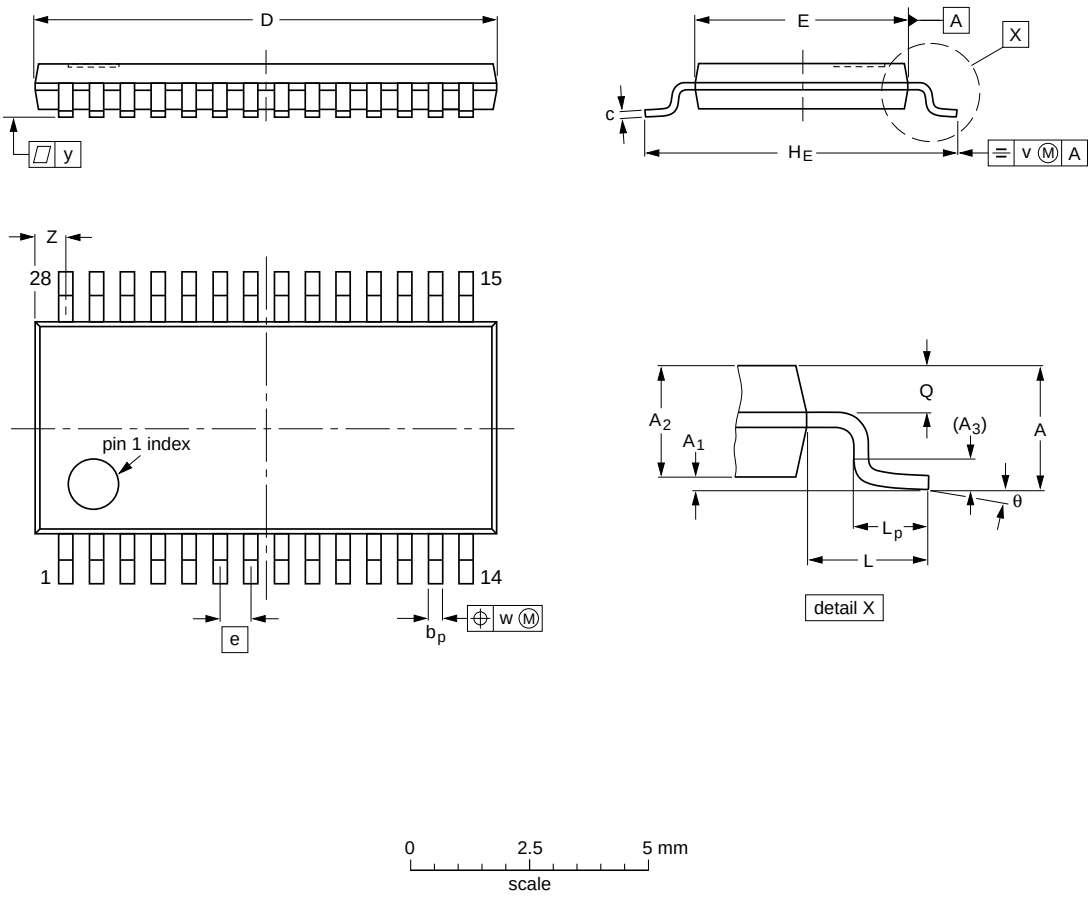
Fig 33. CoreMark score for different Power API modes



V_{DD} = 3.3 V; T = 25 °C; active mode; typical samples. System oscillator enabled; main clock derived from external clock signal; PLL and SYSAHBCLKDIV enabled for frequencies > 20 MHz.

Fig 34. CoreMark current consumption for different power modes using external clock

TSSOP28: plastic thin shrink small outline package; 28 leads; body width 4.4 mm **SOT361-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	9.8 9.6	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.8 0.5	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT361-1		MO-153				~~99-12-27~~ 03-02-19

Fig 56. Package outline SOT361-1 (TSSOP28)

14. Soldering

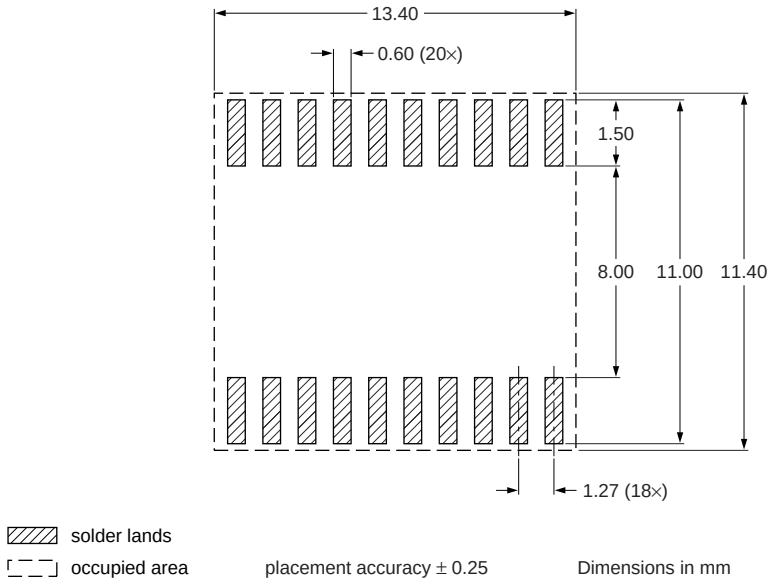
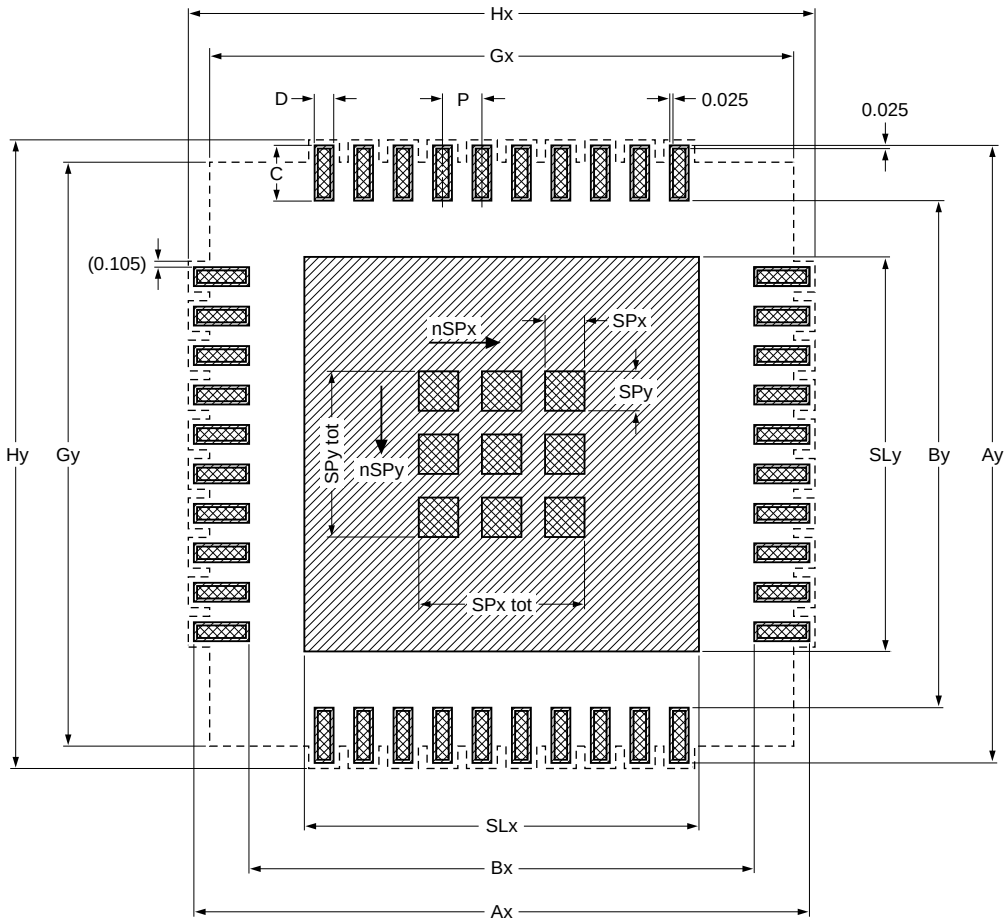


Fig 63. Reflow soldering of the SO20 package

Footprint information for reflow soldering of HVQFN24 package **SOT616-3**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

solder paste deposit

solder land plus solder paste

occupied area

nSPx	nSPy
2	2

Dimensions in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.500	5.000	5.000	3.200	3.200	0.900	0.240	2.500	2.500	1.500	1.500	0.550	0.550	4.300	4.300	5.250	5.250

Issue date ~~07-05-07~~ 09-06-15 *sot616-3_fr*

Fig 66. Reflow soldering of the HVQFN24 package

Footprint information for reflow soldering of HVQFN33 package

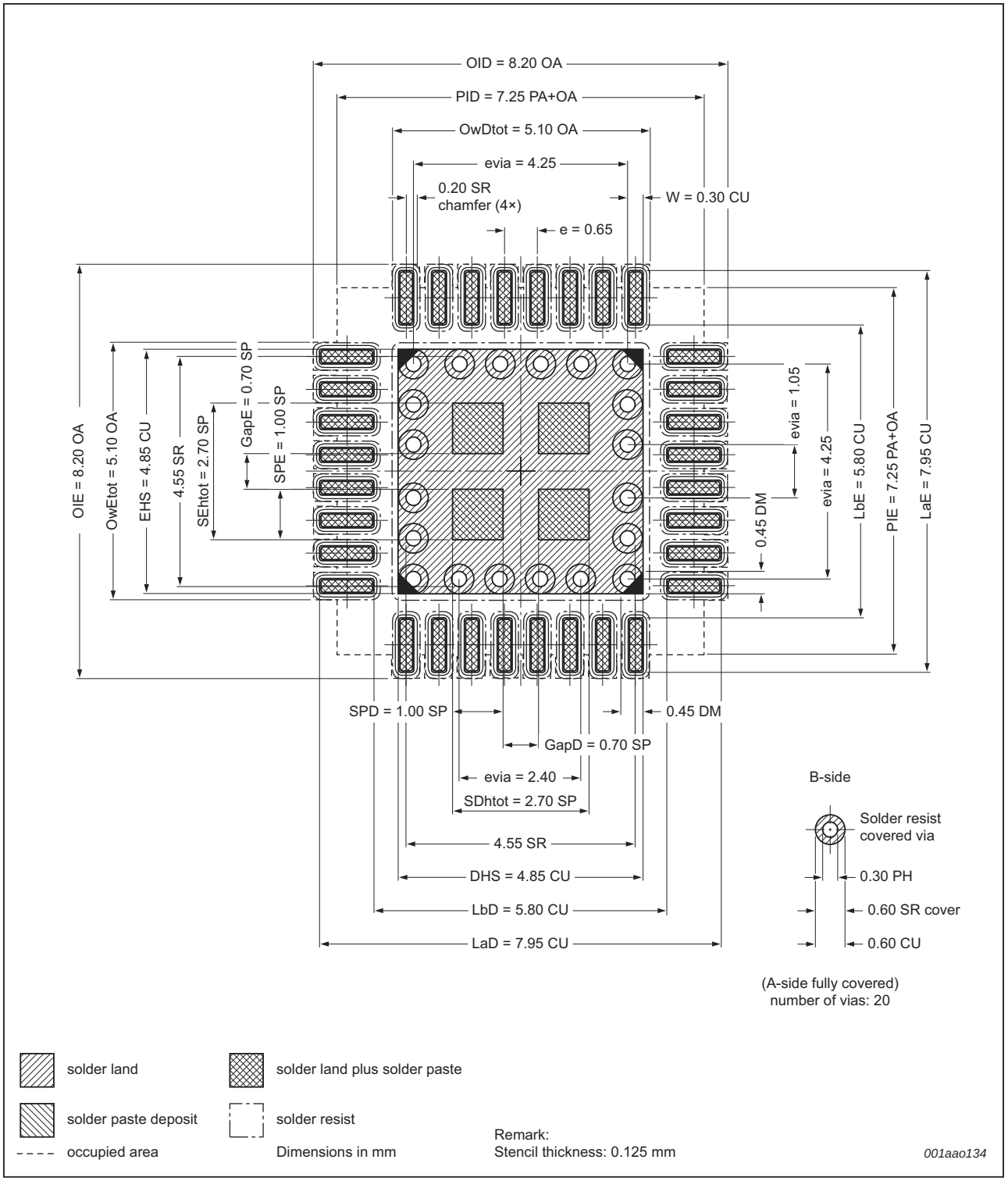


Fig 68. Reflow soldering of the HVQFN33 package (7x7)

18. Legal information

18.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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